

**MOTOROLA**

# *Advance Information*

## **256K x 4 Bit Static Random Access Memory**

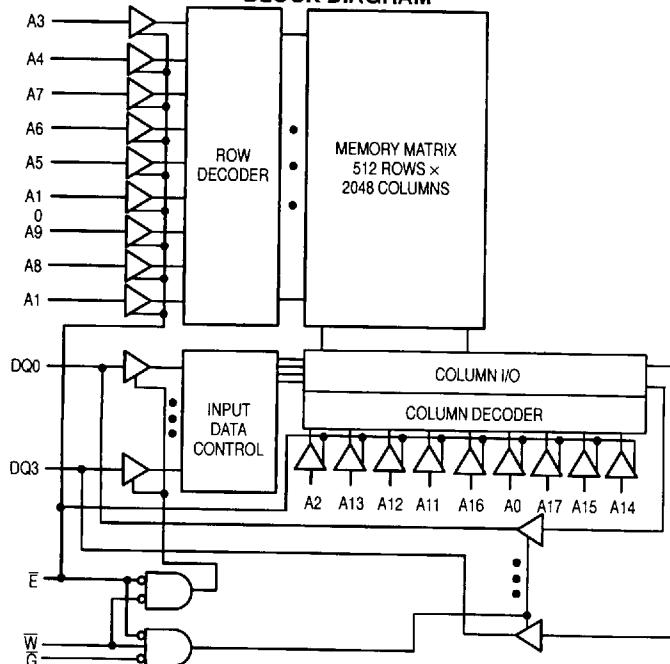
**ELECTRICALLY TESTED PER:  
MPG6229A**

The 6229A is a 1,048,576 bit static random access memory organized as 262,144 words of 4 bits, fabricated using high-performance silicon-gate CMOS technology. Static design eliminates the need for external clocks or timing strobes, while CMOS circuitry reduces power consumption and provides for greater reliability.

The 6229A is equipped with both chip enable ( $\bar{E}$ ) and output enable ( $\bar{G}$ ) pins, allowing for greater system flexibility and eliminating bus contention problems. These devices also incorporate internal power down circuitry that will reduce active current for less than 100% duty cycle applications. These features provide reduced system power requirements without degrading access time performance.

The 6229A is available in a 600 mil ceramic DIL, 550 x 650 mil surface-mount LCC, or a 490 x 830 mil flat-pack.

- Single 5 V ± 10% Power Supply
- Low Power Operation: 170/150/140/130/120/110/90 mA Maximum, Active AC
- Fast Access Time: 6229A: 20/25/35/45/55/70/100 ns
- Equal Address and Chip Enable Access Times
- All Inputs and Outputs are TTL Compatible
- Three-State Outputs

**BLOCK DIAGRAM****6229A**

### **Commercial Plus and Mil/Aero Applications**

**AVAILABLE AS**

- 1) JAN: N/A
  - 2) SMD: N/A
  - 3) 883: 6229A - XX/BXAJC  
**X = CASE OUTLINE AS FOLLOWS:**
- |                 |             |          |
|-----------------|-------------|----------|
| <b>PACKAGE:</b> | <b>DIL:</b> | <b>X</b> |
|                 | <b>LCC:</b> | <b>U</b> |
|                 | <b>FP:</b>  | <b>Y</b> |
- XX = Speed in ns**  
(25, 30, 35, 45, 55, 70, 100)

The letter "M" appears after the speed on LCC

**PIN ASSIGNMENT**

A0	1	•	28	VCC
A1	2		27	A17
A2	3		26	A16
A3	4		25	A15
A4	5		24	A14
A5	6		23	A13
A6	7		22	A12
A7	8		21	A11
A8	9		20	NC
A9	10		19	DQ3
A10	11		18	DQ2
$\bar{E}$	12		17	DQ1
$\bar{G}$	13		16	DQ0
VSS	14		15	W

**PIN NAMES**

A0 – A17	.....	Address Inputs
W	.....	Write Enable
$\bar{G}$	.....	Output Enable
$\bar{E}$	.....	Chip Enable
DQ0 – DQ3	.....	Data Inputs/Outputs
NC	.....	No Connection
VCC	.....	+ 5 V Power Supply
VSS	.....	Ground

This document contains information on a new product. Specifications and information herein are subject to change without notice.

**TRUTH TABLE**

E	G	W	Mode	I/O Pin	Cycle	Current
H	X	X	Not Selected	High-Z	—	I <sub>SB1</sub> , I <sub>SB2</sub>
L	H	H	Output Disabled	High-Z	—	I <sub>CCA</sub>
L	L	H	Read	D <sub>out</sub>	Read	I <sub>CCA</sub>
L	X	L	Write	D <sub>in</sub>	Write	I <sub>CCA</sub>

H = High, L = Low, X = Don't Care

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to these high-impedance circuits.

**ABSOLUTE MAXIMUM RATINGS** (See Note)

Rating	Symbol	Value	Unit
Power Supply Voltage Relative to V <sub>SS</sub>	V <sub>CC</sub>	-0.5 to 7.0	V
Voltage Relative to V <sub>SS</sub> for Any Pin Except V <sub>CC</sub>	V <sub>in</sub> , V <sub>out</sub>	-0.5 to V <sub>CC</sub> + 0.5	V
Output Current (per I/O)	I <sub>out</sub>	± 20	mA
Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>D</sub>	1.1	W
Temperature Under Bias	T <sub>bias</sub>	-10 to +85	°C
Operating Temperature	T <sub>A</sub>	0 to +70	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

**DC OPERATING CONDITIONS AND CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0 V ± 10%, T<sub>A</sub> = -55 to +125°C, Unless Otherwise Noted)**RECOMMENDED OPERATING CONDITIONS**

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Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	V <sub>CC</sub>	4.5	5.5	V
Input High Voltage	V <sub>IH</sub>	2.2	V <sub>CC</sub> + 0.3	V
Input Low Voltage	V <sub>IL</sub>	-0.5*	0.8	V

\*V<sub>IL</sub> (min) = -0.5 V dc; V<sub>IL</sub> (min) = -2.0 V ac (pulse width ≤ 20 ns); V<sub>IH</sub> (max) = V<sub>CC</sub> + 2 V ac (pulse width ≤ 20 ns)**DC CHARACTERISTICS AND SUPPLY CURRENTS**

Parameter	Symbol	Typ*	Min	Max	Unit
Input Leakage Current (All Inputs, V <sub>in</sub> = 0 to V <sub>CC</sub> )	I <sub>kg(I)</sub>	—	-2	2	µA
Output Leakage Current (E = V <sub>IH</sub> , V <sub>out</sub> = 0 to V <sub>CC</sub> )	I <sub>kg(O)</sub>	—	-2	2	µA
AC Active Supply Current (I <sub>out</sub> = 0 mA, V <sub>CC</sub> = max)	I <sub>CCA</sub>	140 120 110 100 90 80 70	— — — — — — —	170 150 140 130 125 120 110	mA
AC Standby Current (V <sub>CC</sub> = 5.5 V, E = V <sub>IH</sub> , f = f <sub>max</sub> )	I <sub>SB1</sub>	10	—	40	mA
CMOS Standby Current (E ≥ V <sub>CC</sub> - 0.2 V V <sub>in</sub> ≤ V <sub>SS</sub> + 0.2 V or ≥ V <sub>CC</sub> - 0.2 V, V <sub>CC</sub> = 5.5 V, f = 0 MHz)	I <sub>SB2</sub>	7	—	30	mA
Output Low Voltage (I <sub>OL</sub> = +8.0 mA)	V <sub>OL</sub>	—	—	0.4	V
Output High Voltage (I <sub>OH</sub> = -4.0 mA)	V <sub>OH</sub>	—	2.4	—	V

\* Typical measurements are taken at 25°C, V<sub>CC</sub> = 5 V.

**CAPACITANCE** ( $f = 1.0 \text{ MHz}$ ,  $dV = 3.0 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ , Periodically Sampled Rather Than 100% Tested)

Characteristic		Symbol	Typ	Max	Unit
Input Capacitance		$C_{in}$ $\bar{E}, \bar{G}, \text{ and } \bar{W}$	6 7	9 10	pF
Input/Output Capacitance	DQ	$C_{i/o}$	10	14	pF

### AC OPERATING CONDITIONS AND CHARACTERISTICS

( $V_{CC} = 5.0 \text{ V} \pm 10\%$ ,  $T_A = -55 \text{ to } +125^\circ\text{C}$ , Unless Otherwise Noted)

Input Pulse Levels .....	0 to 3.0 V	Output Timing Measurement Reference Level .....	1.5 V
Input Rise/Fall Time .....	2 ns	Output Load .....	See Figure 1a
Input Timing Measurement Reference Level .....	1.5 V		

### READ CYCLE TIMING (See Notes 1 and 2)

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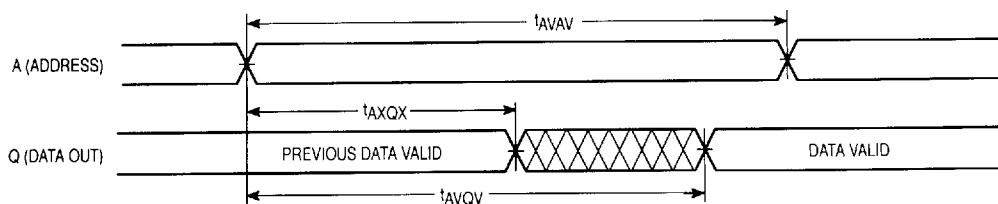
Parameter	Symbol		6229A-25		6229A-30		6229A-35		6229A-45		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max	Min	Max		
Read Cycle Time	$t_{AVAV}$	$t_{RC}$	25	—	30	—	35	—	45	—	ns	2,3
Address Access Time	$t_{AVQV}$	$t_{AA}$	—	25	—	30	—	35	—	45	ns	
Enable Access Time	$t_{ELQV}$	$t_{ACS}$	—	25	—	30	—	35	—	45	ns	4
Output Enable Access Time	$t_{GLQV}$	$t_{OE}$	—	12	—	10	—	15	—	20	ns	
Output Hold from Address Change	$t_{AXQX}$	$t_{OH}$	0	—	0	—	0	—	0	—	ns	
Enable Low before Output Active	$t_{ELQX}$	$t_{ELZ}$	3	—	3	—	3	—	3	—	ns	5,6
Output Enable Low before Output Active	$t_{GLQX}$	$t_{GLZ}$	0	—	0	—	0	—	0	—	ns	5,6
Enable High to Output High-Z	$t_{EHQZ}$	$t_{EHZ}$	0	10	0	10	0	15	0	20	ns	5,6
Output Enable High to Output High-Z	$t_{GHQZ}$	$t_{ELZ}$	0	10	0	10	0	15	0	20	ns	5,6
Power Up Time	$t_{ELICCH}$	$t_{PU}$	0	—	0	—	0	—	0	—	ns	
Power Down Time	$t_{EHICCL}$	$t_{PD}$	—	25	—	30	—	35	—	45	ns	

#### NOTES:

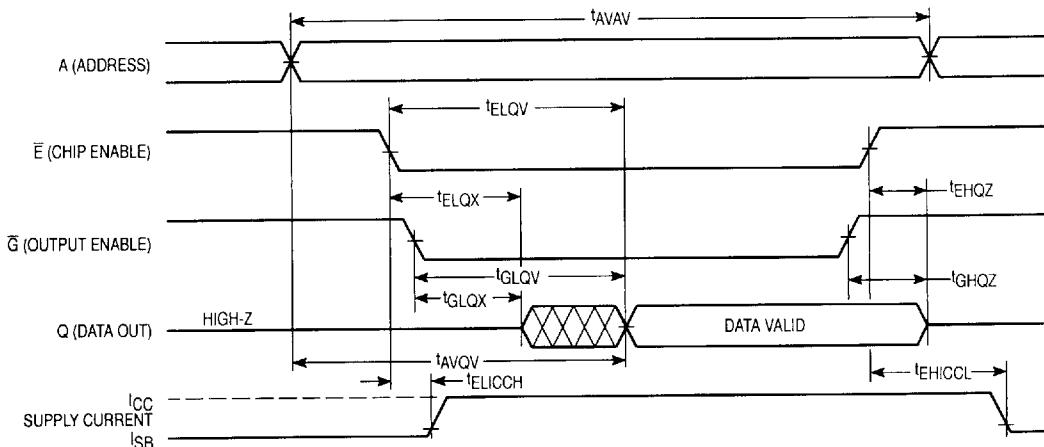
1.  $\bar{W}$  is high for read cycle.
2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
3. All timings are referenced from the last valid address to the first transitioning address.
4. Addresses valid prior to or coincident with  $\bar{E}$  going low.
5. Transition is measured  $\pm 500 \text{ mV}$  from steady-state voltage with load of Figure 1b.
6. This parameter is sampled and not 100% tested.
7. Device is continuously selected ( $\bar{E} \leq V_{IL}$ ,  $\bar{G} \leq V_{IL}$ ).

Parameter	Symbol		6229A-55		6229A-70		6229A-100		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max		
Read Cycle Time	$t_{AVAV}$	$t_{RC}$	55	—	70	—	100	—	ns	2,3
Address Access Time	$t_{AVQV}$	$t_{AA}$	—	55	—	70	—	100	ns	
Enable Access Time	$t_{ELQV}$	$t_{ACS}$	—	55	—	70	—	100	ns	4
Output Enable Access Time	$t_{GLQV}$	$t_{OE}$	—	20	—	25	—	25	ns	
Output Hold from Address Change	$t_{AXQX}$	$t_{OH}$	0	—	0	—	0	—	ns	
Enable Low before Output Active	$t_{ELQX}$	$t_{ELZ}$	3	—	3	—	3	—	ns	5,6
Output Enable Low before Output Active	$t_{GLQX}$	$t_{GLZ}$	0	—	0	—	0	—	ns	5,6
Enable High to Output High-Z	$t_{EHQZ}$	$t_{EHZ}$	0	20	0	30	0	30	ns	5,6
Output Enable High to Output High-Z	$t_{GHQZ}$	$t_{ELZ}$	0	20	0	30	0	30	ns	5,6
Power Up Time	$t_{ELICCH}$	$t_{PU}$	0	—	0	—	0	—	ns	
Power Down Time	$t_{EHICCL}$	$t_{PD}$	—	55	—	70	—	100	ns	

## READ CYCLE 1 (See Notes 1, 2, and 8)



## READ CYCLE 2 (See Note 8)



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WRITE CYCLE 1 ( $\bar{W}$  Controlled, See Notes 1, 2 and 3)

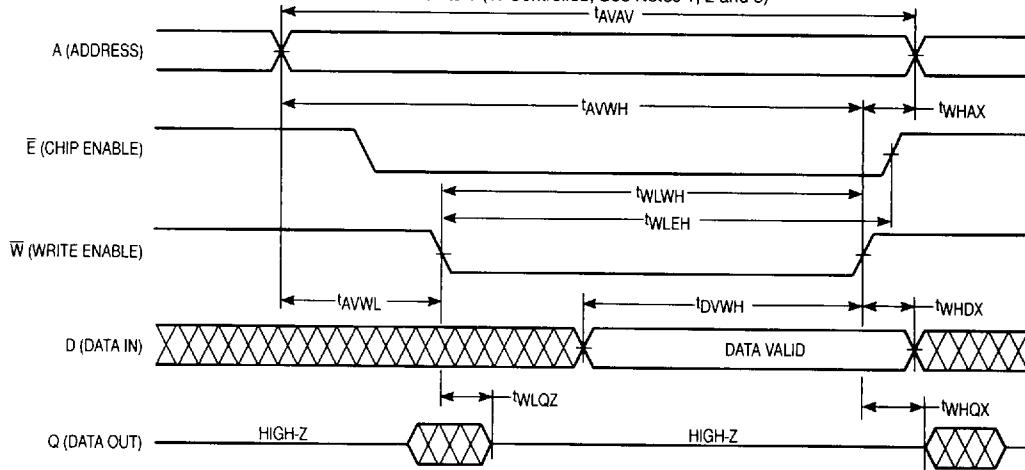
Parameter	Symbol		6229A-25		6229A-30		6229A-35		6229A-45		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	$t_{AVAV}$	$t_{WC}$	25	—	30	—	35	—	45	—	ns	4
Address Setup Time	$t_{AVWL}$	$t_{AS}$	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Write	$t_{AVWH}$	$t_{AW}$	17	—	25	—	30	—	35	—	ns	
Write Pulse Width	$t_{WLWH}$	$t_{WP}$	17	—	25	—	30	—	35	—	ns	
Data Valid to End of Write	$t_{DVWH}$	$t_{DW}$	10	—	15	—	20	—	25	—	ns	
Data Write Hold Time	$t_{WHDX}$	$t_{DH}$	0	—	0	—	0	—	0	—	ns	
Write Enable Time	$t_{WLQZ}$	$t_{WZ}$	0	10	0	10	0	15	0	20	ns	5,6
Write High before Output Active	$t_{WHQX}$	$t_{OW}$	0	—	0	—	0	—	0	—	ns	5,6
Write Address Hold Time	$t_{WHAX}$	$t_{WA}$	5	—	5	—	5	—	5	—	ns	

## NOTES:

1. A write occurs during the overlap of  $\bar{E}$  low and  $\bar{W}$  low.
2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
3. If  $G$  goes low coincident with or after  $\bar{W}$  goes low, the output will remain in a high-impedance state.
4. All timings are referenced from the last valid address to the first transitioning address.
5. Transition is measured  $\pm 500$  mV from steady-state voltage with load of Figure 1b.
6. This parameter is sampled and not 100% tested.

WRITE CYCLE 1 ( $\bar{W}$  Controlled, See Notes 1, 2 and 3)

Parameter	Symbol		6229A-55		6229A-70		6229A-100		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max		
Write Cycle Time	$t_{AVAV}$	$t_{WC}$	55	—	70	—	100	—	ns	4
Address Setup Time	$t_{AVWL}$	$t_{AS}$	0	—	0	—	0	—	ns	
Address Valid to End of Write	$t_{AVWH}$	$t_{AW}$	35	—	45	—	45	—	ns	
Write Pulse Width	$t_{WLWH}$	$t_{WP}$	35	—	40	—	40	—	ns	
Data Valid to End of Write	$t_{DVWH}$	$t_{DW}$	30	—	35	—	40	—	ns	
Data Write Hold Time	$t_{WHDX}$	$t_{DH}$	0	—	0	—	0	—	ns	
Write Enable Time	$t_{WLQZ}$	$t_{WZ}$	0	20	0	30	0	35	ns	5,6
Write High before Output Active	$t_{WHQX}$	$t_{OW}$	0	—	0	—	0	—	ns	5,6
Write Address Hold Time	$t_{WHAX}$	$t_{WA}$	5	—	5	—	5	—	ns	5,6

WRITE CYCLE 1 ( $\bar{W}$  Controlled, See Notes 1, 2 and 3)

AC TEST LOADS

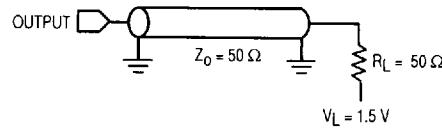


Figure 1a

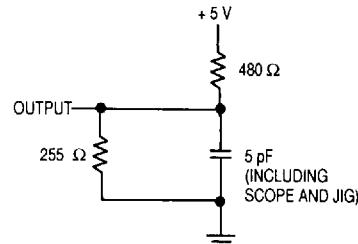


Figure 1b

## TIMING LIMITS

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

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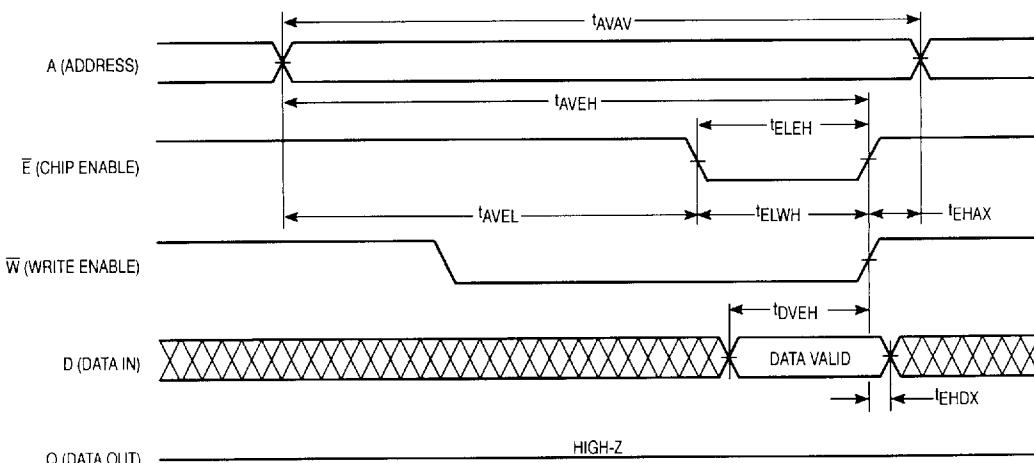
WRITE CYCLE 2 ( $\bar{E}$  Controlled, See Notes 1, 2 and 3)

Parameter	Symbol		6229A-25		6229A-30		6229A-35		6229A-45		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	$t_{AVAV}$	$t_{WC}$	25	—	30	—	35	—	45	—	ns	4
Address Setup Time	$t_{AVEL}$	$t_{AS}$	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Enable	$t_{AVEH}$	$t_{AE}$	17	—	15	—	20	—	25	—	ns	
Enable Write Pulse Width	$t_{ELEH}$	$t_{EP}$	17	—	20	—	25	—	35	—	ns	5,6
Enable to End of Write Window	$t_{ELWH}$	$t_{EW}$	17	—	20	—	25	—	35	—	ns	
Write to End of Enable Window	$t_{WLEH}$	$t_{WE}$	17	—	20	—	25	—	35	—	ns	
Data Valid to End of Enable	$t_{DVEH}$	$t_{DE}$	10	—	15	—	20	—	25	—	ns	
Data Enable Hold Time	$t_{EHDX}$	$t_{DH}$	0	—	0	—	0	—	0	—	ns	
Enable Address Hold Time	$t_{EHAX}$	$t_{EH}$	5	—	5	—	5	—	5	—	ns	

## NOTES:

1. A write occurs during the overlap of  $\bar{E}$  low and  $\bar{W}$  low.
2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
3. If  $\bar{G}$  goes low coincident with or after  $\bar{W}$  goes low, the output will remain in a high-impedance state.
4. All timings are referenced from the last valid address to the first transitioning address.
5. If  $\bar{E}$  goes low coincident with or after  $\bar{W}$  goes low, the output will remain in a high-impedance state.
6. If  $\bar{E}$  goes high coincident with or before  $\bar{W}$  goes high, the output will remain in a high-impedance state.

Parameter	Symbol		6229A-25		6229A-30		6229A-100		Unit	Notes
	Standard	Alternate	Min	Max	Min	Max	Min	Max		
Write Cycle Time	$t_{AVAV}$	$t_{WC}$	25	—	35	—	45	—	ns	4
Address Setup Time	$t_{AVEL}$	$t_{AS}$	0	—	0	—	0	—	ns	
Address Valid to End of Enable	$t_{AVEH}$	$t_{AE}$	30	—	35	—	40	—	ns	
Enable Write Pulse Width	$t_{ELEH}$	$t_{EP}$	35	—	40	—	40	—	ns	5,6
Enable to End of Write Window	$t_{ELWH}$	$t_{EW}$	35	—	45	—	45	—	ns	
Write to End of Enable Window	$t_{WLEH}$	$t_{WE}$	35	—	45	—	45	—	ns	
Data Valid to End of Enable	$t_{DVEH}$	$t_{DE}$	30	—	35	—	40	—	ns	
Data Enable Hold Time	$t_{EHDX}$	$t_{DH}$	0	—	0	—	0	—	ns	
Enable Address Hold Time	$t_{EHAX}$	$t_{EH}$	5	—	5	—	5	—	ns	

WRITE CYCLE 2 ( $\bar{E}$  Controlled, See Notes 1, 2 and 3)

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